

**ABSTRACT**

A film carrier tape for mounting electronic devices thereon has a tin-bismuth alloy deposit in which bismuth content in the deposit is substantially uniform along a thickness direction thereof. The film carrier tape can be produced by plating at least a part of a wiring pattern with a tin-bismuth alloy and washing the tin-bismuth alloy deposit formed by plating with a water-ejecting washing nozzle within 6 seconds after the plating is completed. A plating apparatus for use in the above production includes a washing nozzle for washing the film carrier tape within 6 seconds after the film carrier tape has exited a plating tank.